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|---|---|---|---|---|---|
| | | | | | |

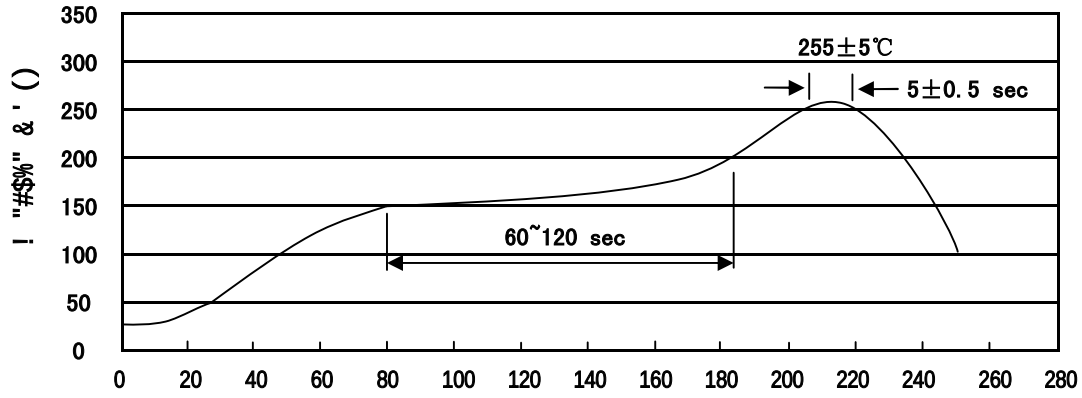
SOT-23 N MOS N-CHANNEL MOSFET in a SOT-23 Plastic Package.

=>?$ - /67$5"!"

Low $R_{DS(on)}$,rugged and reliable, compact industry standard SOT-23 surface mount pac a ac

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Drain-Source Voltage | $V_{DSS}$ | 50 | V |
| Gate-Source Voltage | $V_{GSS}$ | ±20 | V |
| Drain Current – Continuous | $I_D$ | 220 | mA |
| Peak Drain Current | $I_{DM}$ | 880 | mA |
| Power Dissipation | $P_D$ | 360 | mW |
| Thermal Resistance, Junction-to- | | | |

## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)




说明：

1、预热温度 150～200 ，时间 60～120sec;

2、峰值温度 255±5 ，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:150~200℃, Time:60~120sec.

2.Peak Temp.:255±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

## / Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

## / Packaging SPEC.

卷盘包装 / REEL

| Package Type ! | Units " # $ | | | | | Dimension " % & (unit ' mm$^3$) | | |
|---|---|---|---|---|---|---|---|---|
| | Units/Reel 只/卷盘 | Reels/Inner Box 卷盘/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Reel | Inner Box ( | Outer Box ) |
| SOT-23 | 3,000 | 10 | 30,000 | 6 | 180,000 | 7″ ×8 | 180×120×180 | 390×385×205 |

## / Notices